

Ministry of Electronics & IT



Prime Minister Shri Narendra Modi Inaugurates SEMICON India 2026; Unveils India's Ambitious Roadmap for Transition to Semicon 2.0, with Expanded Support for Design, Manufacturing, Packaging, R&D and Talent Development

PM Interacts with Young Chip Designers and Students; Encourages Them to Drive India's Semiconductor Future

PM Calls upon Global Industry to Partner in Building a Complete Semiconductor Ecosystem in India

PM Launches New Commercial Semiconductor Production Lines: India Moves from Policy to Production

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Prime Minister Shri Narendra Modi today inaugurated SEMICON India 2026 to be held from 17-19 September 2026 in New Delhi. Addressing the occasion and highlighting the significance of the event's fifth edition, the Prime Minister extended warm greetings to all participants. He expressed gratitude to the international attendees who had traveled to India to participate in the summit.

Hosted at Yashobhoomi, SEMICON India 2026 features over 600 exhibitors, including approximately 300 international participants, six country pavilions and twelve Indian state pavilions. It also includes a Startup Pavilion and a Workforce Development Zone. On first day, there were about 12,000 visitors at the event.

Shri Ajit Manocha, President & CEO, SEMI, said the global semiconductor market is forecast to reach USD 3 trillion by 2035 and urged India to build indispensable capabilities across key value-chain segments.

Shri Sanjay Mehrotra, CEO, Micron Technology, said commercial DRAM and NAND production is live at Sanand, Gujarat.

Mr. Jochen Hanebeck, CEO, Infineon Technologies, highlighted the company's 2,800+ employees in India, its skilling partnership with NIELIT and opportunities in power semiconductors, smart mobility and automotive electrification.

Dr. Randhir Thakur, CEO & MD, Tata Electronics, confirmed that the construction of Dholera 300mm fab and Jagiroad OSAT facility is on track. He informed that Tata Electronics shall be signing 7 MoUs in the areas including inter-alia semiconductor wafer manufacturing, assembly and test; building advanced semiconductor packaging capabilities; supply of photoresists and advanced chemicals for fab; localization of critical semiconductor materials, and talent development, with Fujifilm, Nexperia, BESI Singapore Pte. Ltd, JSR Corporation etc.

Mr. Toshiki Kawai, CEO, Tokyo Electron, committed support for India's upcoming wafer fabs and advanced packaging facilities and announced a semiconductor training centre in Gujarat next year in partnership with the Government of Japan.

Mr. Benjamin Hein, CEO Electronics, Merck, emphasized that fab viability requires parallel local investment in ultra-pure semiconductor chemicals and gases, safe materials handling and certified domestic suppliers.

Dr. Prabu Raja, President, SPG, Applied Materials, announced 'India Vision 2035': a USD 5 billion investment over the next decade and tenfold expansion of its India-based supply-chain capacity by 2035.

Shri Shesha Varadarajan, COO, Lam Research, announced approximately ₹10,000 crore for the company's first silicon-component manufacturing and vertical ingot-processing plant in India, and said its Semiverse programme has reached over 99 universities.

Mr. Wayne Allan, EVP, ASML, reiterated its partnership with Tata Electronics for lithography solutions at the Dholera fab and said ASML is considering the possibility of integrating Indian suppliers for its global supply chain.

Shri Ashwini Vaishnaw, Union Minister for Electronics & IT, Railways, and I&B noted that while foundational groundwork has been done under Semicon 1.0, including 70,000 design engineers trained and EDA tools deployed across 500+ organizations, Semicon 2.0 scales ecosystem development across six comprehensive pillars: Design, Equipment & Materials, Fabs, Advanced Packaging, Applied R&D and Talent.

The Prime Minister Shri Narendra Modi interacted with 20 students from academic institutions across the country who presented a memento of 20 chips, designed, fabricated and tested for various applications.

Prime Minister Shri Narendra Modi virtually inaugurated commercial production lines at CDIL Semiconductor, Mohali for discrete devices and Suchi Semicon, Surat for packaging. This has resulted in five operational commercial semiconductor ATMP units, alongside Micron, Kaynes, and CG Semi, out of the twelve approved units under Semicon 1.0.



Addressing the gathering, Prime Minister Shri Narendra Modi highlighted India's execution velocity and macro resilience with 7.8% quarterly GDP growth, 3,000 km of operational dedicated freight corridors, a sovereign rating upgrade and a successful BRICS Summit hosted by India. Outlining the relentless momentum of the sector, the Prime Minister highlighted the expansion of the India Semiconductor Mission budget from USD 8 billion in Semicon 1.0 to USD 13.5 billion for Semicon 2.0.

Detailing the vision for a robust domestic supply chain, the Prime Minister urged leaders in equipment, chemicals, gases, and materials to capitalize on the golden opportunities presented by the twelve approved projects and an expanding demand pipeline. "We want the entire ecosystem to grow together," asserted the Prime Minister.

At the Conference, Secretary, MeitY, Shri S. Krishnan declared that India has "truly arrived" in the semiconductor space, announcing the transition to Semicon 2.0 after committing its initial six-year funding phase in just four years.

MoUs and Strategic Announcements

Strategic MoUs and announcements spanning design, fabrication, packaging, materials, equipment and skills involved Tata Electronics, Kaynes Semicon, Intel, Nexperia, CDIL Semiconductors and their partners. Key outcomes included India's first commercial QFN chip by Suchi Semicon and eInfochips, integration of the India-designed SenseSoC-200 chip into smart meters, six ChipIN Regional Centres and HORIBA India's KOACH Experience Centre.

Addressing the media, Union Minister Shri Ashwini Vaishnaw outlined 'Semicon 2.0', marking India's transition from foundational credibility to comprehensive domestic capability.



India–USA Country Roundtable – Semiconductor & Electronics Ecosystem

The India-USA Country Roundtable brought together government and industry representatives from 64 Indian companies and 52 international organisations. Discussions focused on commercial partnerships, joint ventures, R&D, supply chains and skills across the semiconductor and electronics value chain.

India–Japan Semiconductor Roundtable

The India-Japan Semiconductor Roundtable focused on combining Japan's strengths in equipment, materials and precision manufacturing with India's demand, design talent and expanding manufacturing base through joint ventures, technology transfers, localized supply chains and R&D.

Focused Sessions

The opening day featured focused sessions charting India's transition from foundational policy planning to large-scale execution across the silicon value chain. These sessions covered AI-enabled chip design and manufacturing, advanced packaging, next-generation manufacturing, equipment R&D and workforce development.

SEMICON India 2026 which runs till September 19th at Yashobhoomi, New Delhi, features more than 600 participating companies and is expected to attract around 50,000 visitors, with representatives from 52 countries, more than 400 executives and over 150 speakers. The exhibition features six Country Pavilions representing Japan, South Korea, Malaysia, the Netherlands, Singapore and Sweden, along with 12 State booths, a Startup Pavilion, Innovation Showcase, Student Hackathon and Workforce Development Pavilion.

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